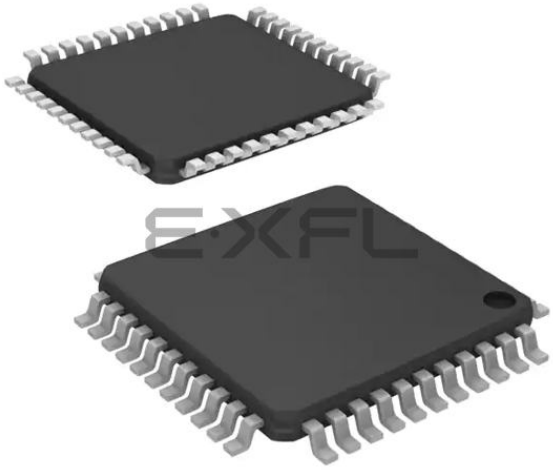

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm104-i-pt

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not exceeding 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3 or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site (www.microchip.com).

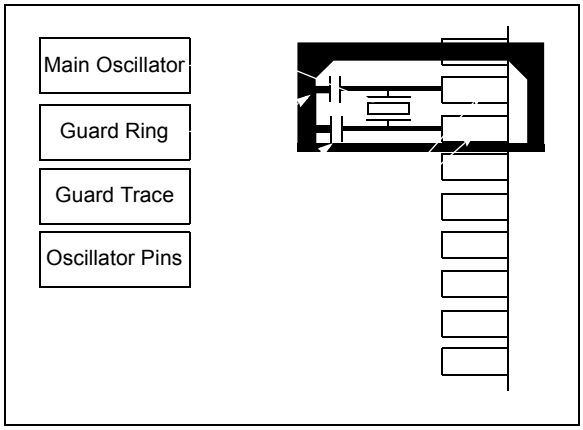
- *"Using MPLAB® ICD 3"* (poster) (DS51765)
- *"MPLAB® ICD 3 Design Advisory"* (DS51764)
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* (DS51616)
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) (DS51749)

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For more information, see **Section 9.0 "Oscillator Configuration"**.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed as shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 5 MHz < F_{IN} < 13.6 MHz to comply with device PLL start-up conditions. This intends that, if the external oscillator frequency is outside this range, the application must start up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLFBD, to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source.

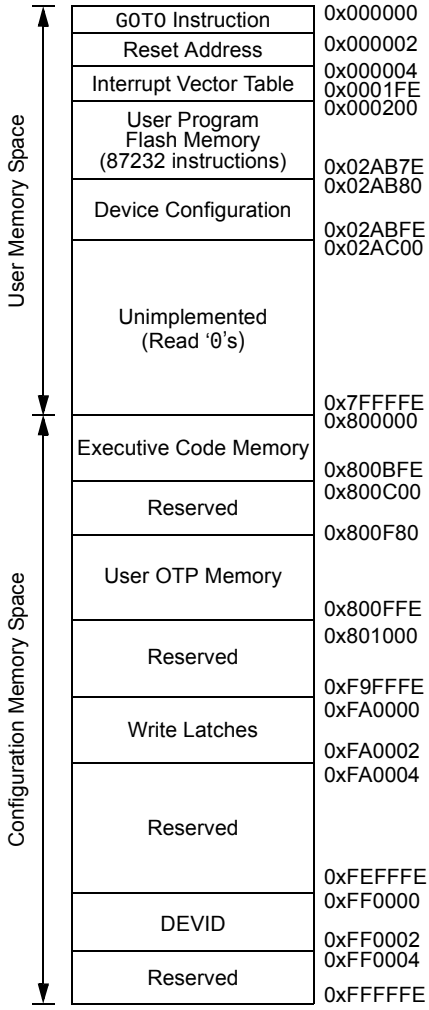
Note:	Clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

Alternatively, connect a 1k to 10k resistor between V_{SS} and unused pins, and drive the output to logic low.

FIGURE 4-4: PROGRAM MEMORY MAP FOR dsPIC33EV256GM00X/10X DEVICES(1)



Note 1: Memory areas are not shown to scale.

TABLE 4-39: PORTD REGISTER MAP FOR dsPIC33EVXXXGMX06 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISD	0E3C	—	—	—	—	—	—	—	TRISD8	—	TRISD<6:5>		—	—	—	—	—	0160
PORTD	0E3E	—	—	—	—	—	—	—	RD8	—	RD<6:5>		—	—	—	—	—	xxxx
LATD	0E40	—	—	—	—	—	—	—	LATD8	—	LATD<6:5>		—	—	—	—	—	xxxx
ODCD	0E42	—	—	—	—	—	—	—	ODCD8	—	ODCD<6:5>		—	—	—	—	—	0000
CNEND	0E44	—	—	—	—	—	—	—	CNIED8	—	CNIED<6:5>		—	—	—	—	—	0000
CNPUD	0E46	—	—	—	—	—	—	—	CNPUD8	—	CNPUD<6:5>		—	—	—	—	—	0000
CNPDD	0E48	—	—	—	—	—	—	—	CNPDD8	—	CNPDD<6:5>		—	—	—	—	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-40: PORTE REGISTER MAP FOR dsPIC33EVXXXGMX06 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISE	0E50	TRISE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	F000
PORTE	0E52	RE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	xxxx
LATE	0E54	LATE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	xxxx
ODCE	0E56	ODCE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
CNENE	0E58	CNIEE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPUE	0E5A	CNPUE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPDE	0E5C	CNPDE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	0000
ANSELE	0E5E	ANSE<15:12>				—	—	—	—	—	—	—	—	—	—	—	—	F000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 9-3: PLLFBD: PLL FEEDBACK DIVISOR REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	PLLDIV8
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
PLLDIV<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8-0 **PLLDIV<8:0>:** PLL Feedback Divisor bits (also denoted as 'M', PLL multiplier)

111111111 = 513
•
•
•
000110000 = 50 (default)
•
•
•
000000010 = 4
000000001 = 3
000000000 = 2

Note 1: This register is reset only on a Power-on Reset (POR).

REGISTER 11-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC2R7	IC2R6	IC2R5	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC1R7	IC1R6	IC1R5	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **IC2R<7:0>:** Assign Input Capture 2 (IC2) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

bit 7-0 **IC1R<7:0>:** Assign Input Capture 1 (IC1) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 11-5: RPINR8: PERIPHERAL PIN SELECT INPUT REGISTER 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC4R7	IC4R6	IC4R5	IC4R4	IC4R3	IC4R2	IC4R1	IC4R0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC3R7	IC3R6	IC3R5	IC3R4	IC3R3	IC3R2	IC3R1	IC3R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **IC4R<7:0>:** Assign Input Capture 4 (IC4) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

bit 7-0 **IC3R<7:0>:** Assign Input Capture 3 (IC3) to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 11-16: RPINR44: PERIPHERAL PIN SELECT INPUT REGISTER 44

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SENT1R<7:0>							
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **SENT1R<7:0>:** Assign SENT Module Input 1 to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

bit 7-0 **Unimplemented:** Read as '0'

REGISTER 11-17: RPINR45: PERIPHERAL PIN SELECT INPUT REGISTER 45

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SENT2R<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **SENT2R<7:0>:** Assign SENT Module Input 2 to the Corresponding RPn Pin bits
(see Table 11-2 for input pin selection numbers)
10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000= Input tied to Vss

REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1 (CONTINUED)

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)(3)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
•
•
•
000 = Secondary prescale 8:1

bit 1-0 **PPRE<1:0>:** Primary Prescale bits (Master mode)(3)
11 = Primary prescale 1:1
10 = Primary prescale 4:1
01 = Primary prescale 16:1
00 = Primary prescale 64:1

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).

2: This bit must be cleared when FRMEN = 1.

3: Do not set both primary and secondary prescalers to the value of 1:1.

21.2 UART Control Registers

REGISTER 21-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)
- 1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by UEN<1:0>
- 0 = UARTx is disabled; all UARTx pins are controlled by PORT latches; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** UARTx Stop in Idle Mode bit
- 1 = Discontinues module operation when the device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)
- 1 = IrDA encoder and decoder are enabled
- 0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Pin Enable bits
- 11 = UxTX, UxRX and BCLKx pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches(3)
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used(4)
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches(4)
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLKx pins are controlled by PORT latches

bit 7 **WAKE:** UARTx Wake-up on Start bit Detect During Sleep Mode Enable bit
- 1 = UARTx continues to sample the UxRX pin; interrupt is generated on the falling edge, bit is cleared in hardware on the following rising edge
- 0 = Wake-up is not enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Loopback mode is enabled
- 0 = Loopback mode is disabled

Note 1: Refer to **"Universal Asynchronous Receiver Transmitter (UART)"** (DS70000582) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.

2: This feature is only available for the 16x BRG mode (BRGH = 0).

3: This feature is only available on 44-pin and 64-pin devices.

4: This feature is only available on 64-pin devices.

REGISTER 22-6: CxINTF: CANx INTERRUPT FLAG REGISTER

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN
bit 15							bit 8

R/C-0	R/C-0	R/C-0	U-0	R/C-0	R/C-0	R/C-0	R/C-0
IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **TXBO:** Transmitter in Error State Bus Off bit
1 = Transmitter is in Bus Off state
0 = Transmitter is not in Bus Off state

bit 12 **TXBP:** Transmitter in Error State Bus Passive bit
1 = Transmitter is in Bus Passive state
0 = Transmitter is not in Bus Passive state

bit 11 **RXBP:** Receiver in Error State Bus Passive bit
1 = Receiver is in Bus Passive state
0 = Receiver is not in Bus Passive state

bit 10 **TXWAR:** Transmitter in Error State Warning bit
1 = Transmitter is in Error Warning state
0 = Transmitter is not in Error Warning state

bit 9 **RXWAR:** Receiver in Error State Warning bit
1 = Receiver is in Error Warning state
0 = Receiver is not in Error Warning state

bit 8 **EWARN:** Transmitter or Receiver in Error State Warning bit
1 = Transmitter or receiver is in Error Warning state
0 = Transmitter or receiver is not in Error Warning state

bit 7 **IVRIF:** Invalid Message Interrupt Flag bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **WAKIF:** Bus Wake-up Activity Interrupt Flag bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **ERRIF:** Error Interrupt Flag bit (multiple sources in CxINTF<13:8> register)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **Unimplemented:** Read as '0'

bit 3 **FIFOIF:** FIFO Almost Full Interrupt Flag bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 2 **RBOVIF:** RX Buffer Overflow Interrupt Flag bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

TABLE 27-1: CONFIGURATION WORD REGISTER MAP (CONTINUED)

File Name	Address	Device Memory Size (Kbytes)	Bits 23-16	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FDMTINTVL	0057AC	32	—	DMTIVT<15:0>															
	00ABAC	64																	
	0157AC	128																	
	02ABAC	256																	
FDMTINTVH	0057B0	32	—	DMTIVT<31:16>															
	00ABB0	64																	
	0157B0	128																	
	02ABB0	256																	
FDMTCNTL	0057B4	32	—	DMTCNT<15:0>															
	00ABB4	64																	
	0157B4	128																	
	02ABB4	256																	
FDMTCNTH	0057B8	32	—	DMTCNT<31:16>															
	00AB8	64																	
	0157B8	128																	
	02ABB8	256																	
FDMT	0057BC	32	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	DMTEN
	00ABBC	64																	
	0157BC	128																	
	02ABBC	256																	
FDEVOPT	0057C0	32	—	—	—	—	—	—	—	—	—	—	—	—	—	ALTI2C1	Reserved(2)	—	PWMLOCK
	00ABC0	64																	
	0157C0	128																	
	02ABC0	256																	
FALTREG	0057C4	32	—	—	—	—	—	—	—	—	—	—	CTXT2<2:0>			—	CTXT1<2:0>		
	00ABC4	64																	
	0157C4	128																	
	02ABC4	256																	

Legend: — = unimplemented, read as '1'.

Note 1: This bit is reserved and must be programmed as '0'.

2: This bit is reserved and must be programmed as '1'.

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage(3)**	VBOR	—	5.5	V	
DC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	1.0	—	—	V/ms	0V-5.0V in 5 ms
DC18	VCORE	**VDD Core** Internal Regulator Voltage	1.62	1.8	1.98	V	Voltage is dependent on load, temperature and VDD

Note 1: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

2: This is the limit to which VDD may be lowered without losing RAM data.

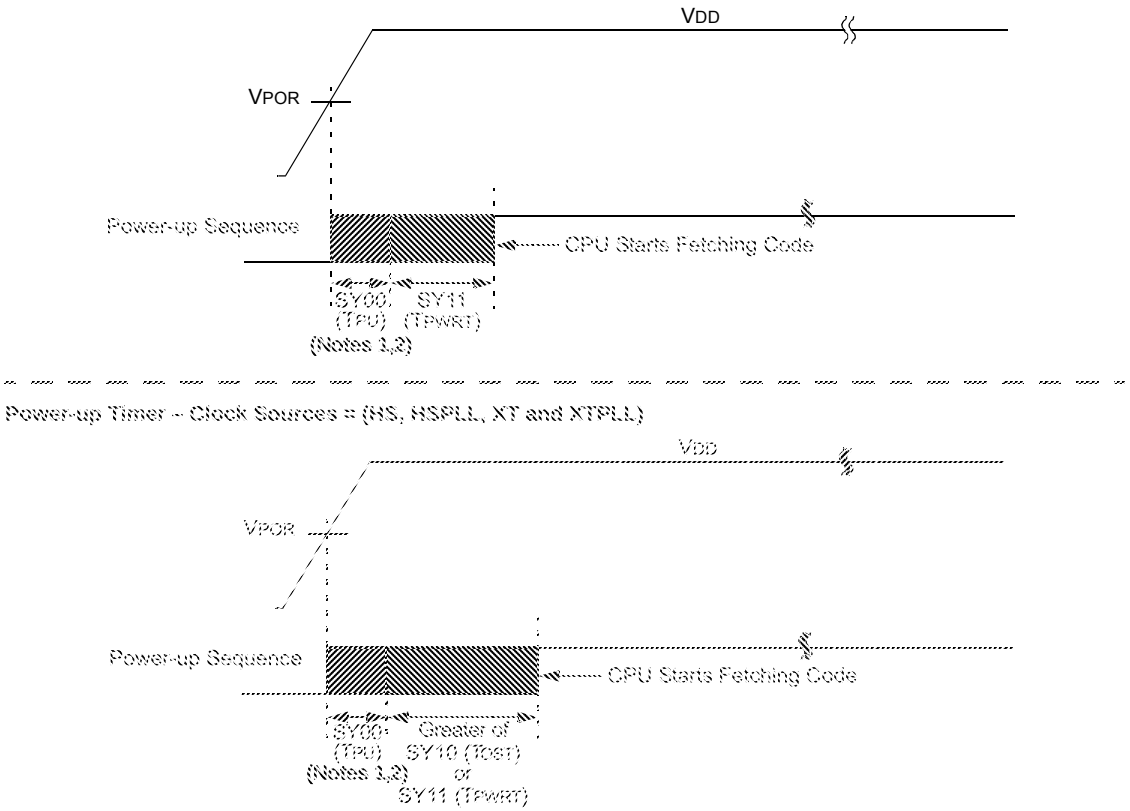
3: VDD voltage must remain at VSS for a minimum of 200 μs to ensure POR.

TABLE 30-5: FILTER CAPACITOR (CEFC) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated): Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
	CEFC	External Filter Capacitor Value(1)	4.7	10	—	μF	Capacitor must have a low series resistance (< 1Ω)

Note 1: Typical VCAP Voltage = 1.8 volts when VDD ≥ VDDMIN.

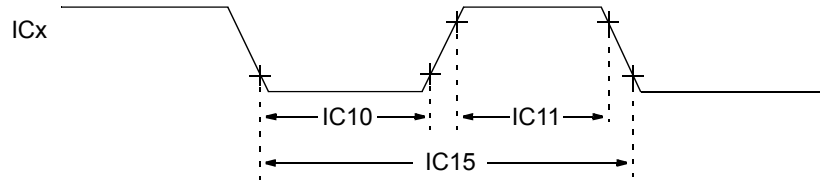
FIGURE 30-5: POWER-ON RESET TIMING CHARACTERISTICS



Note 1: The power-up period will be extended if the power-up sequence completes before the device exits from BOR ($V_{DD} < V_{BOR}$).

2: The power-up period includes internal voltage regulator stabilization delay.

FIGURE 30-7: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS



Note 1: Refer to Figure 30-1 for load conditions.

TABLE 30-26: INPUT CAPTURE x (ICx) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TccL	ICx Input Low Time	Greater of: 12.5 + 25 or (0.5 TCY/N) + 25	—	ns	Must also meet Parameter IC15	N = Prescaler Value (1, 4, 16)
IC11	TccH	ICx Input High Time	Greater of: 12.5 + 25 or (0.5 TCY/N) + 25	—	ns	Must also meet Parameter IC15	
IC15	TccP	ICx Input Period	Greater of: 25 + 50 or (1 TCY/N) + 50	—	ns		

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-10: HIGH-SPEED PWMx MODULE FAULT TIMING CHARACTERISTICS

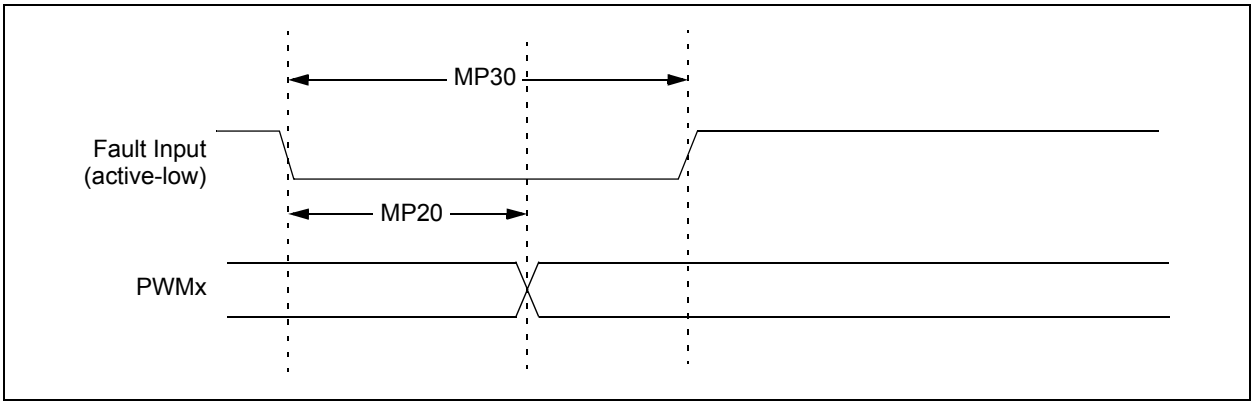
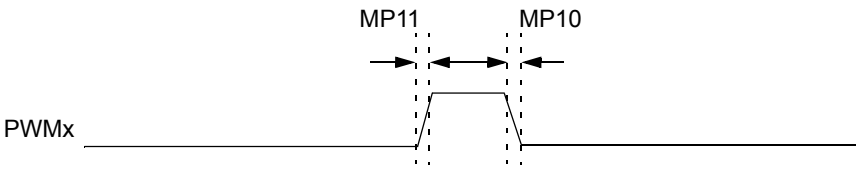


FIGURE 30-11: HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS



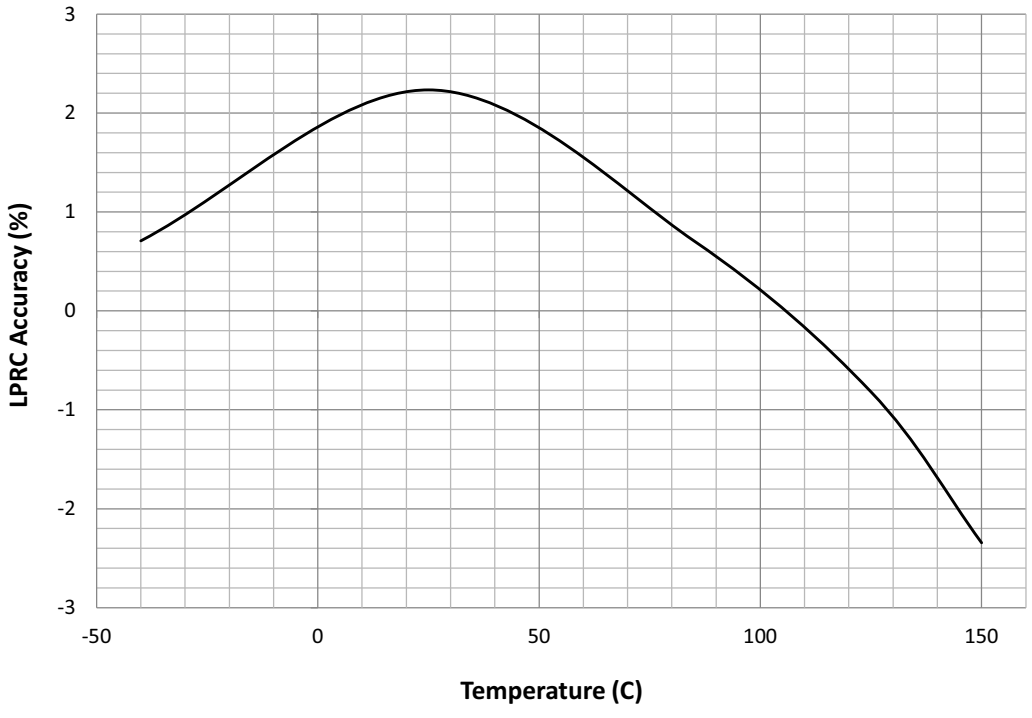
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MP10	TFPWM	PWMx Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWMx Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWMx I/O Change	—	—	15	ns	
MP30	TFH	Fault Input Pulse Width	15	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 32-23: TYPICAL LPRC ACCURACY vs. TEMPERATURE (5.5V VDD)



32.7 Leakage Current

FIGURE 32-24: TYPICAL IIL vs. TEMPERATURE (MCLR)

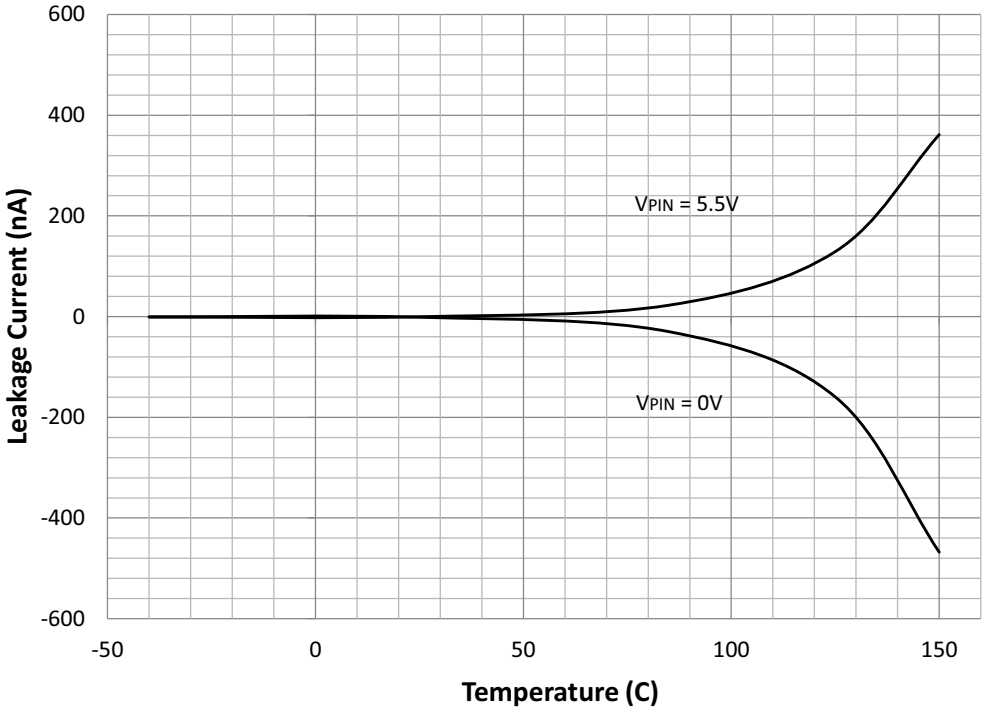


FIGURE 33-7: TYPICAL IIDLE vs. VDD (EC MODE, 20 MIPS)

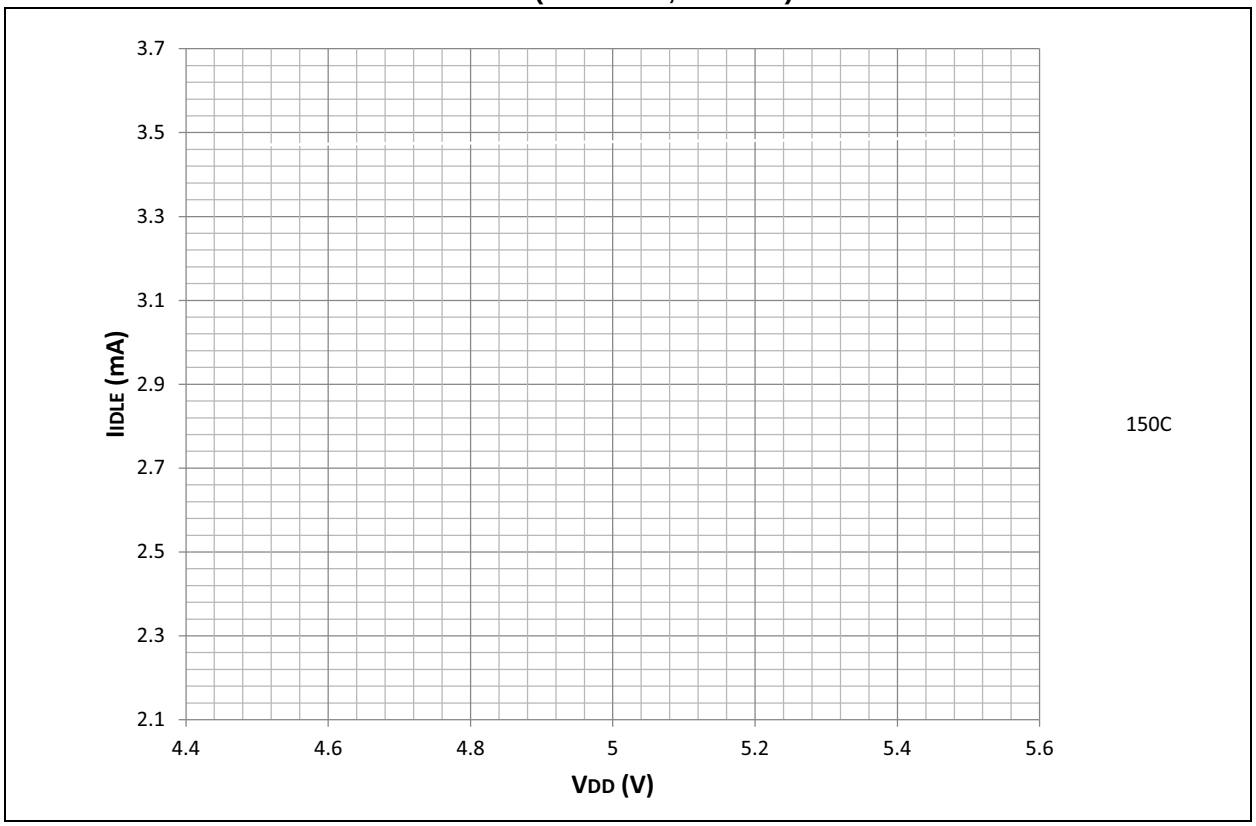


FIGURE 33-8: TYPICAL IIDLE vs. VDD (EC MODE, 40 MIPS)

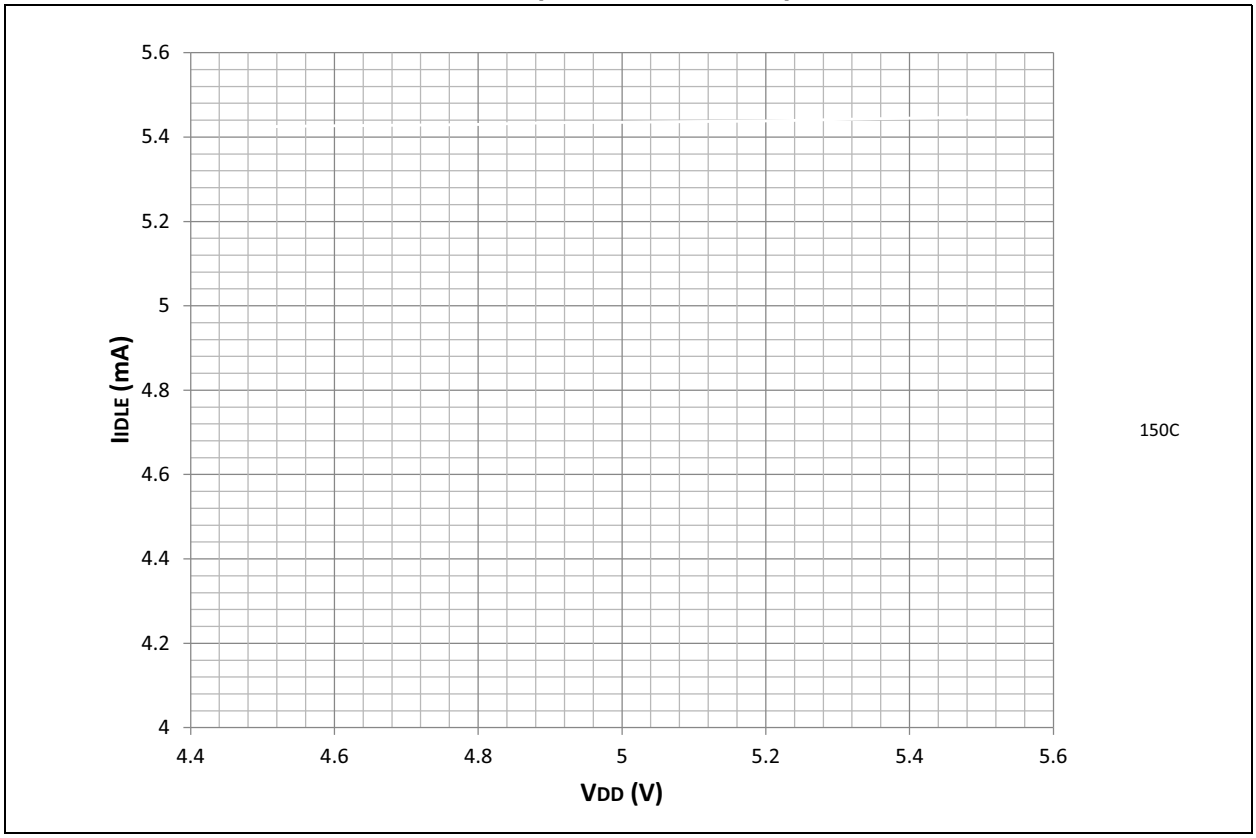


FIGURE 33-21: TYPICAL IIL vs. TEMPERATURE (OSC1)

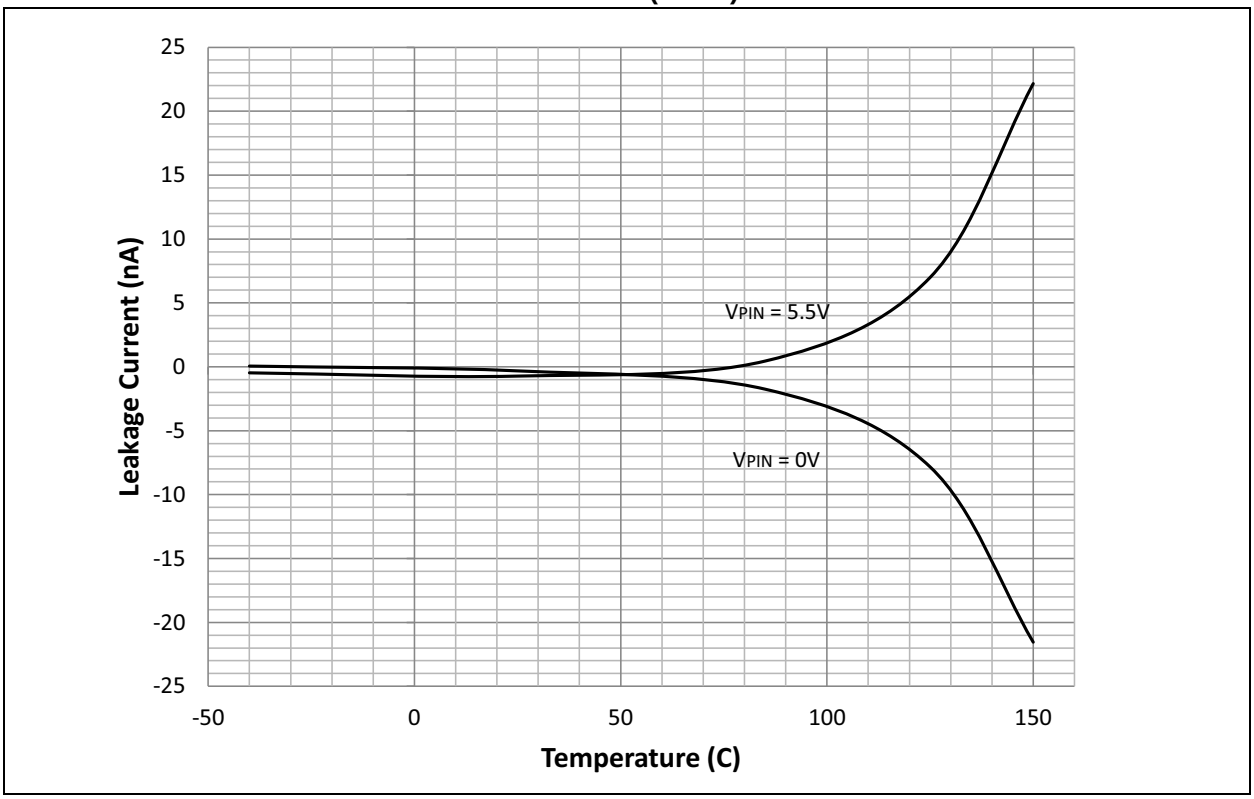
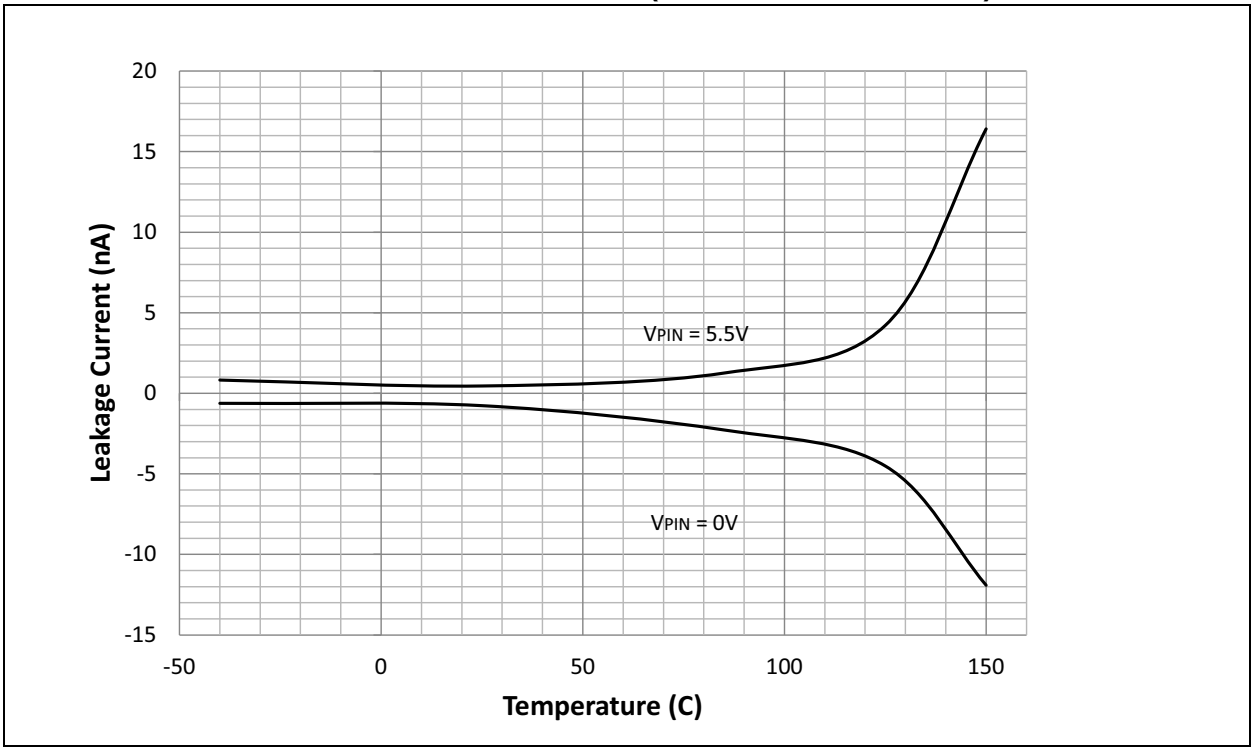
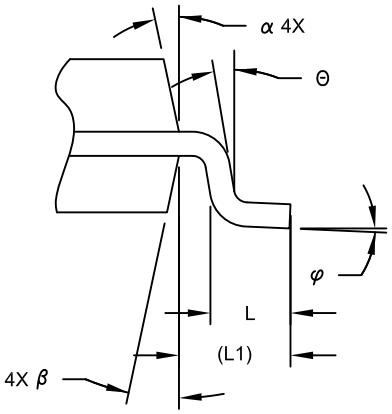


FIGURE 33-22: TYPICAL IIL vs. TEMPERATURE (GENERAL PURPOSE I/Os)

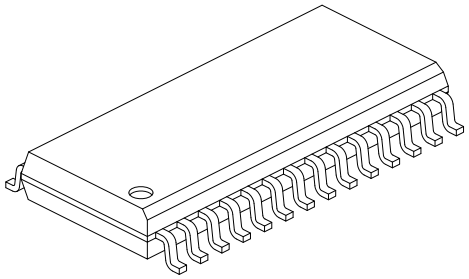


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

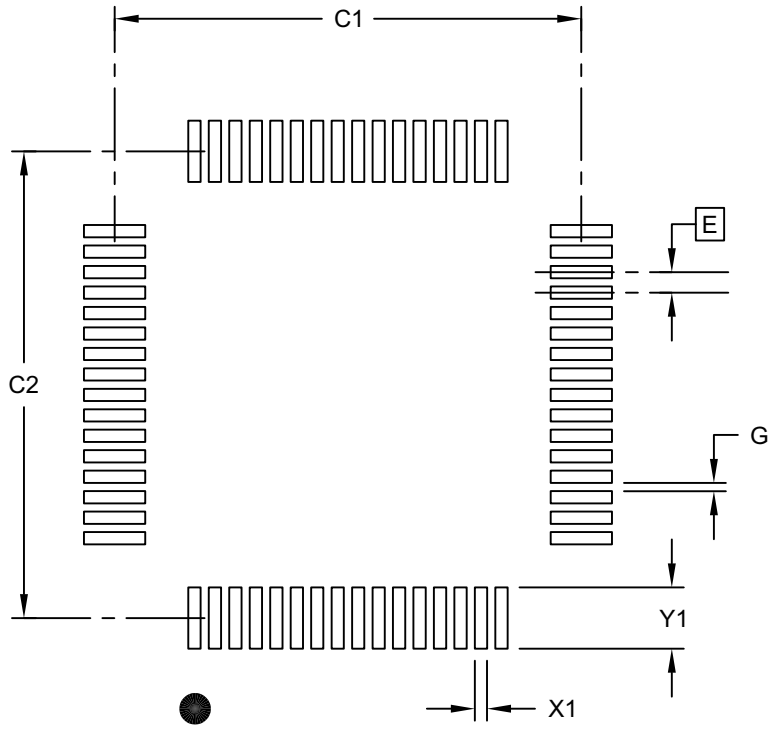
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X28)	X1			0.30
Contact Pad Length (X28)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2085B Sheet 1 of 1